

Ultrafast X-Ray Imager (UXI) Focal Plane Array Testing & Characterization

Overview


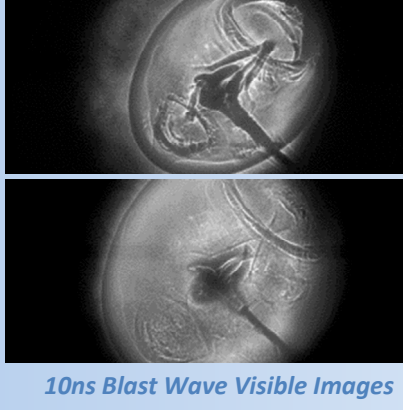
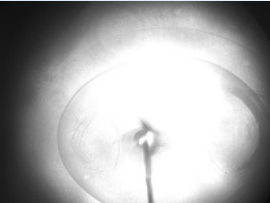
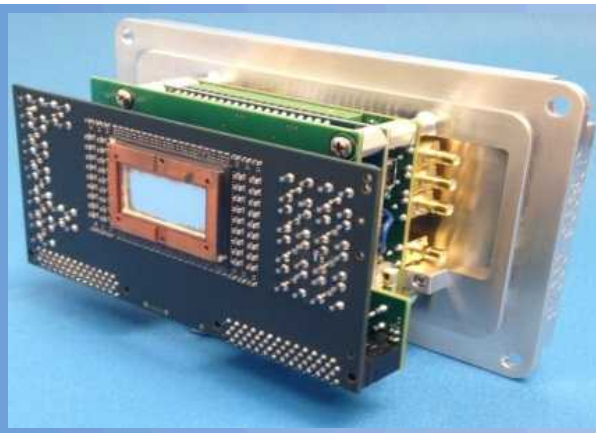
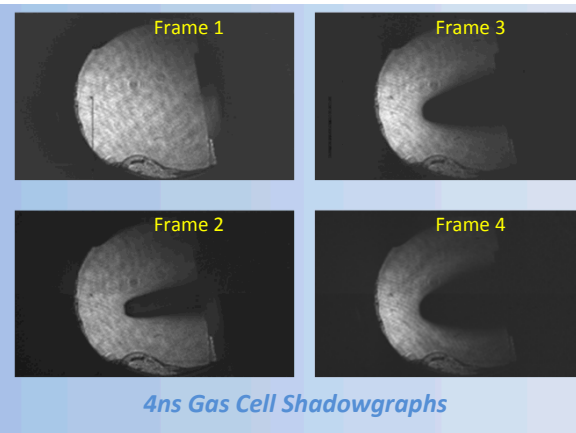
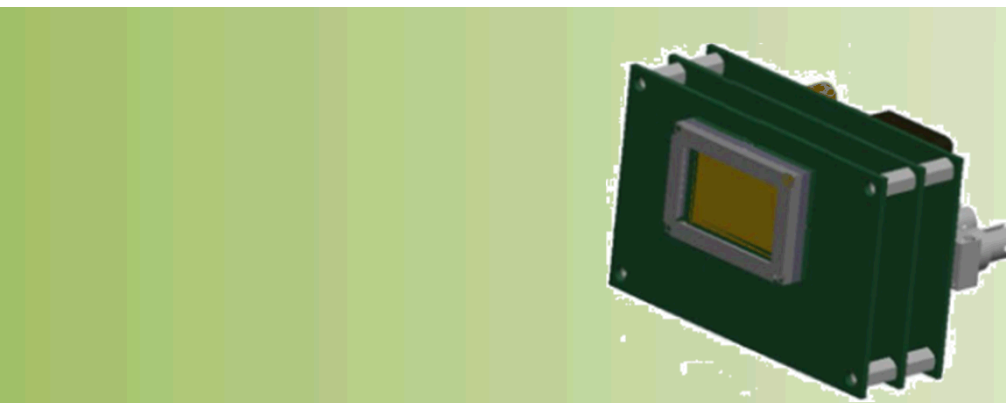
Name: **Casey Petersen**
 School: **Arizona State University**
 Degree: **Bachelors of Science in Engineering (Electrical Systems)**
 Graduating: **December 2015**

Manager: **Michael Holmes**
 Mentor: **Marcos Sanchez**
 Organization: **1753; Mixed Signal ASIC/SoC Products**
 Location: **Sandia National Laboratories - New Mexico**

UXI overview

The Ultra-Fast X-ray Imager (UXI) program is an ongoing effort to create high speed, multi-frame, time gated imagers for High Energy Density physics experiments. UXI enables the collection of higher quality data, produced faster, with a lower cost, resulting in improved weapon/fusion modeling and research.

UXI Focal Plane Arrays

FURI 1.5ns, 2 Frames 448x1024 pixels 350nm Sandia Process			VS.  <small>Commercial Double Exposed CCD</small>	FY14
HIPPOGRIFF 1.5ns, 2-8 Frames (Interlacing) 448x1024 pixels 350nm Sandia Process			FY15	
ICARUS 1.5ns, 4 Frames 512x1024 pixels 350nm Sandia Process		FY16		

Main Project

Problem Statement: The UXI team needs automated test systems to assist in testing and characterizing Focal Plane Arrays (FPAs) at different stages in the assembly process



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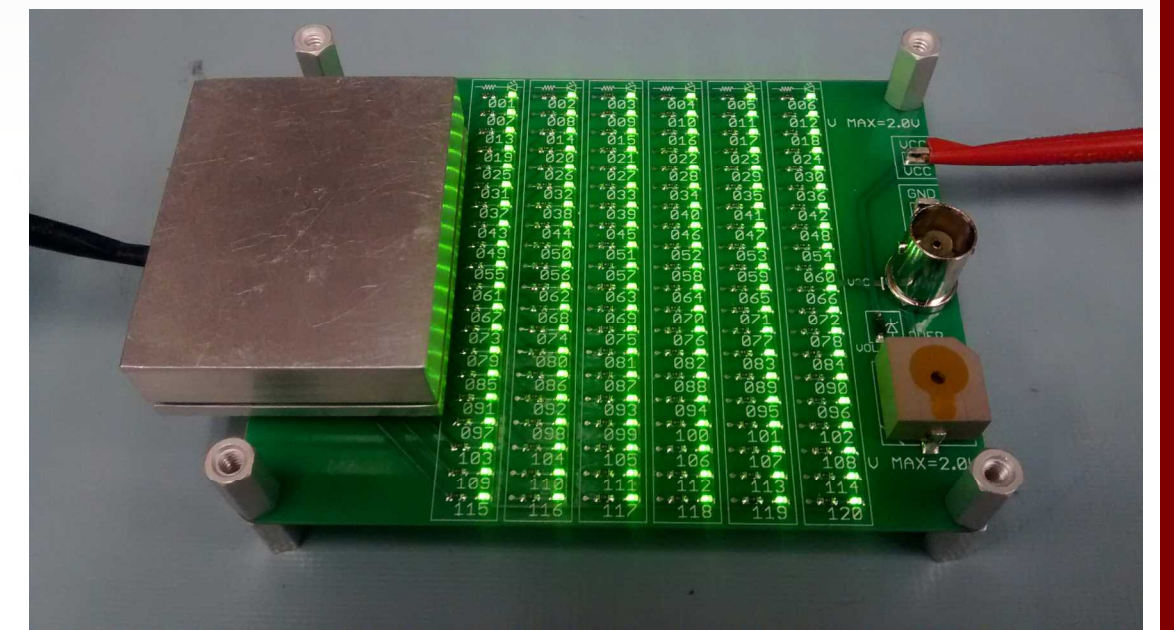
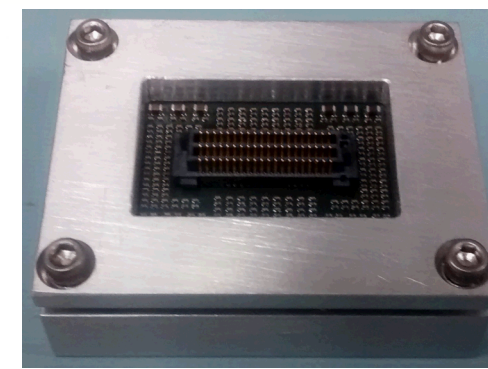
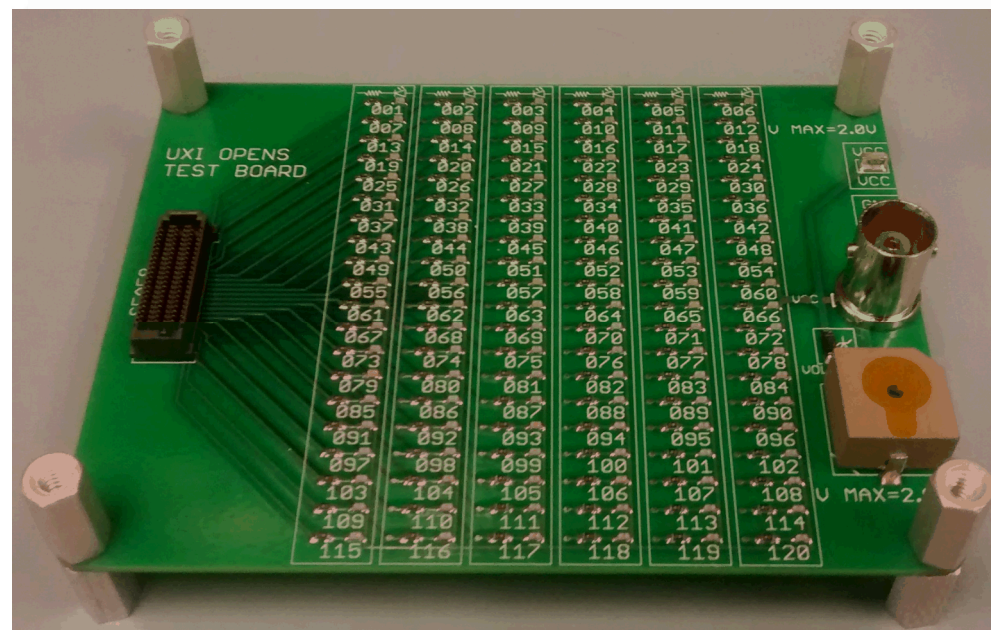
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Projects

1. UXI Small Outline Package Opens Test Board

- Developed a Printed Circuit Board that tests for open solder connections on the connector of an FPA package

Impact: Previously there was no method in place to test for opens

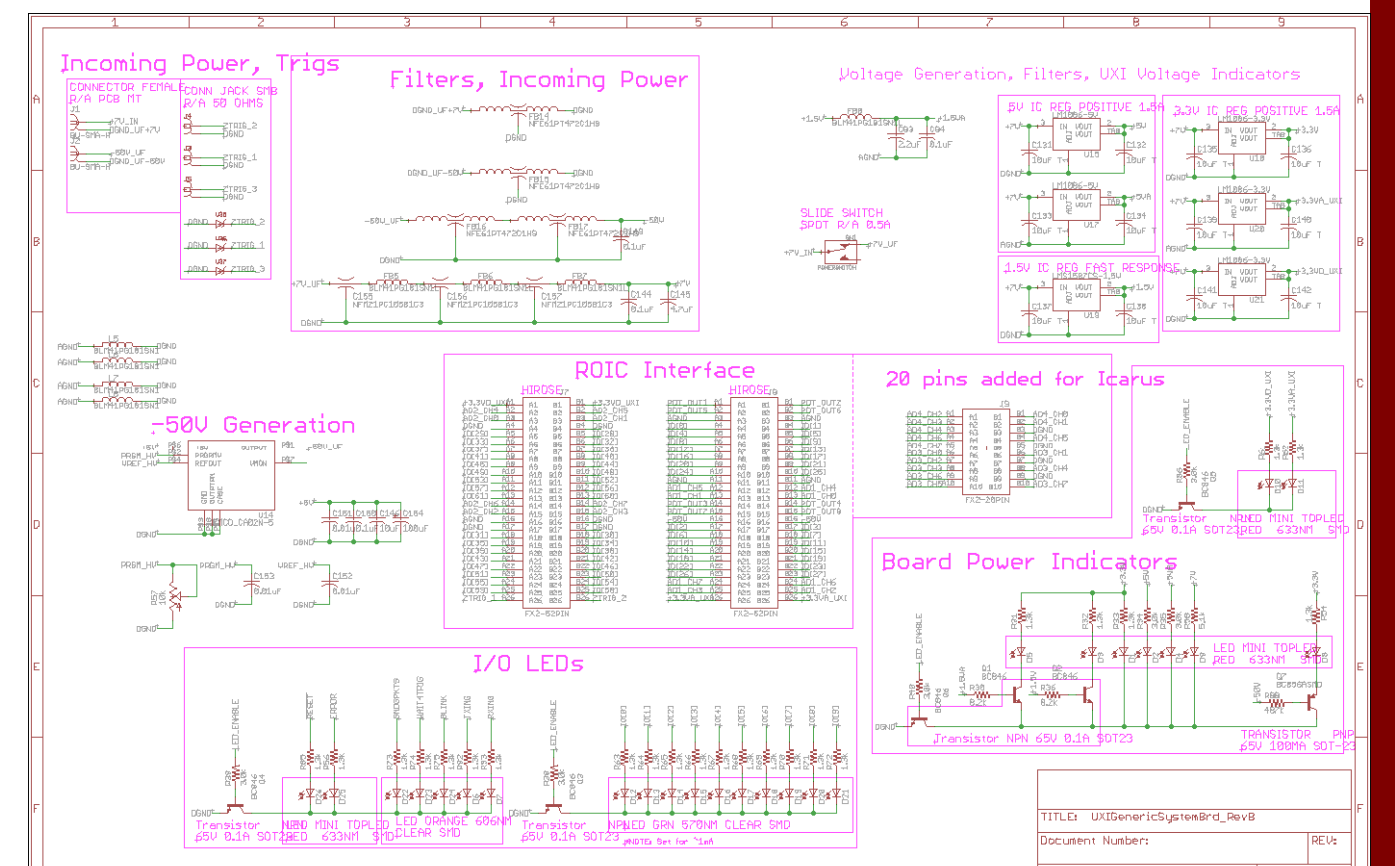
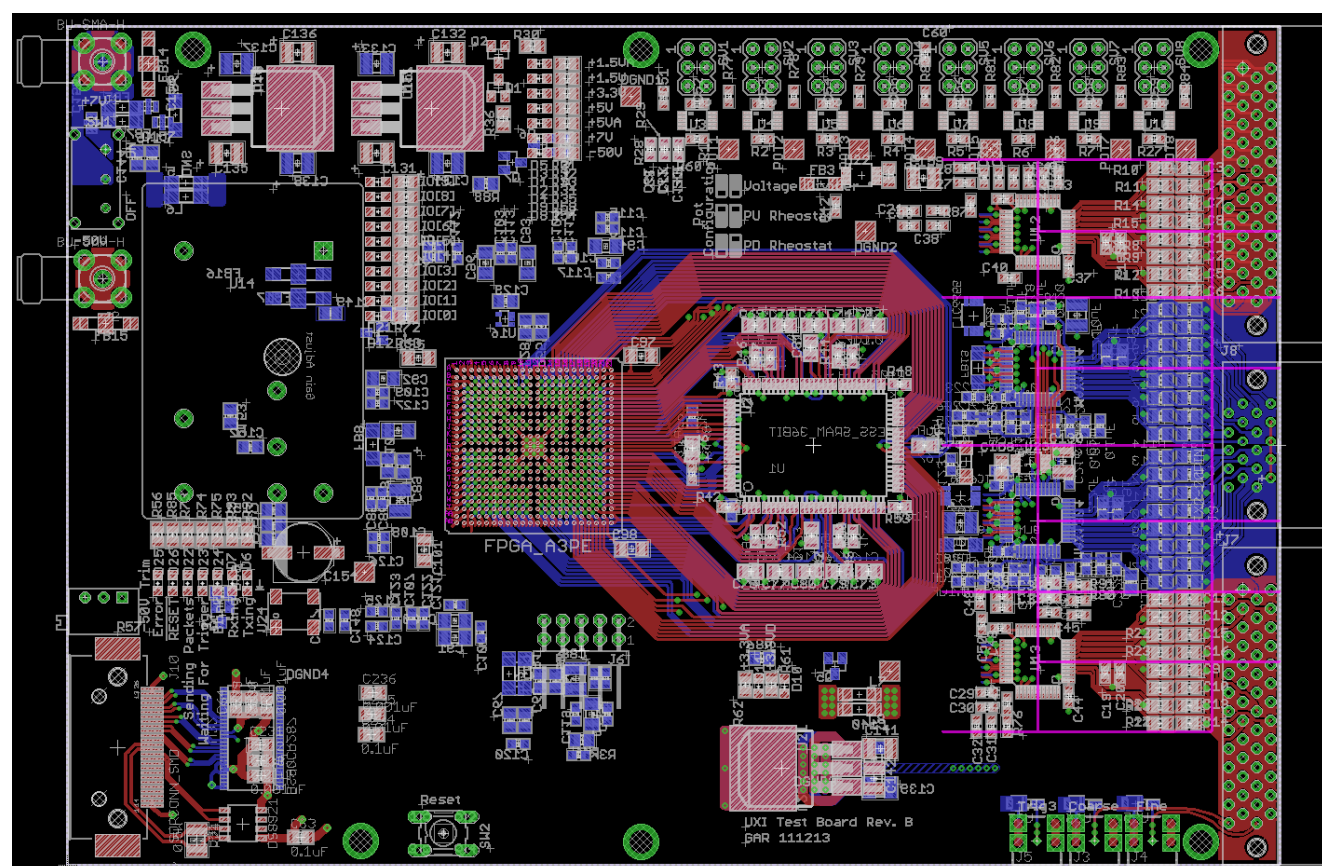


2. UXI FPA Evaluation Board (Main Project)

- Designed an electrical system to test and characterize the focal plane arrays of the three most recent UXI FPAs

Impact: Enables the UXI team to look at the FPAs in greater detail before shipping them to a customer

- Allows the customer to test and characterize their system and troubleshoot it themselves if needed



2. Designing a vacuum feedthrough PCB for a pulse dilation camera capable of 20ps imaging

- Revolutionary new camera for high energy density physics being developed with general atomics for use in the national ignition facility and z-machine

Conclusions

I worked in a team with one other intern under the direction of our mentor while interfacing with customers, manufacturers, and vendors to successfully complete our projects. I learned about Sandia's design process while strengthening my skills in circuit design and PCB layout; specifically in the areas of parallel data capture, signals shielding, signal buffering, and designing for testability (DFT).



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